

# Some EGS Studies...

- Compare with Geant4
  - Questions of range/cutoff
- EM Resolution understood?
- Moliere radius – readout gap relation
- Input shower widths for fast MC
- Calibration requirement (electronics design)
- ECal depth
  - containment
  - Transverse/long. segmentation for pattern recognition
  - Optimize coarser sampling with depth
- Minimum number of silicon layers (30? 25? 20??)

# EGS4 Setup

	1.5 mm	0.5	0.68	0.32	0.25	0.5	1.5
	W bulk	W thin	G 10	Si	Air	W thin	W bulk
	E cut = 500 keV	100 keV	100 keV	100 keV		100 keV	500 keV
→	P cut = 500 keV	100 keV	100 keV	20 keV		100 keV	500 keV
	E stepe = 0.3%	0.3%	0.3%	0.3%		0.3%	0.3%

Config: 30 x [ 5/7 X0 (2.5 mm) + 1.25 mm gaps]

## Thin EM sampling (Si)

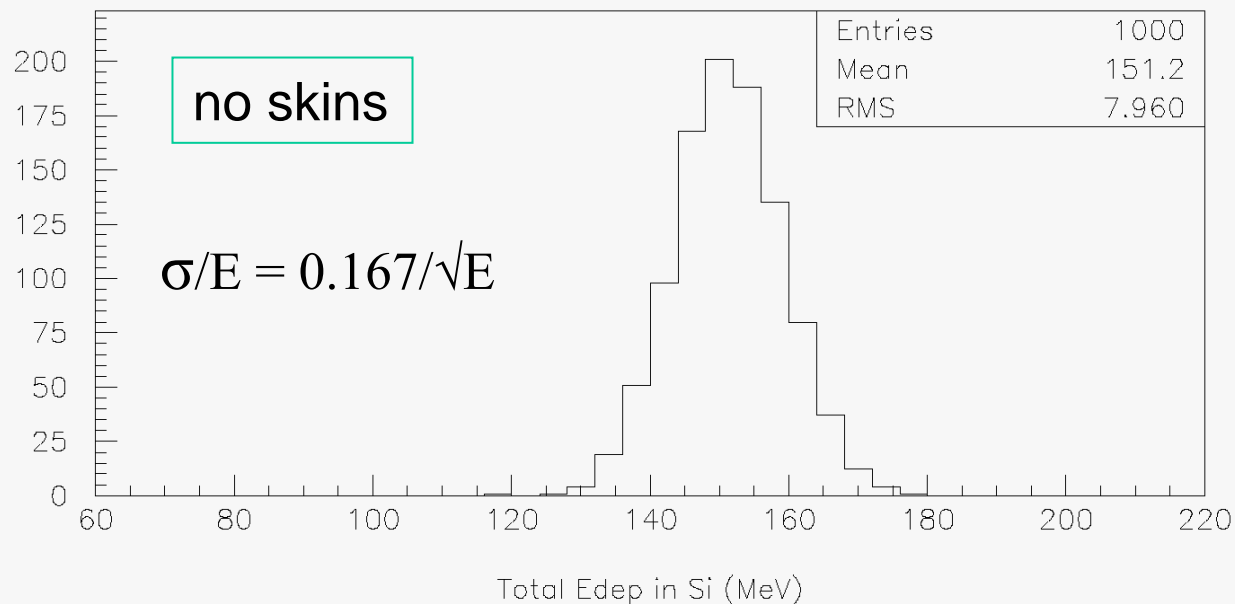
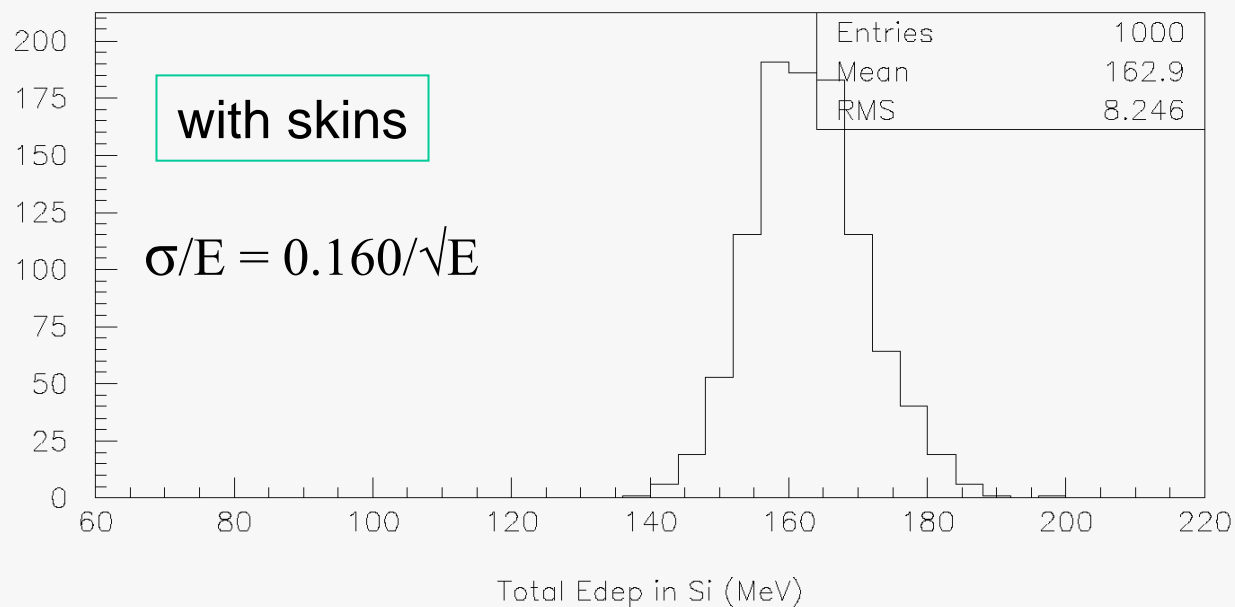
If energy cutoffs (EGS) are too large, then the simulated range of low energy secondaries exceeds the physical range

⇒ Their energy doesn't get deposited in the sensitive region.

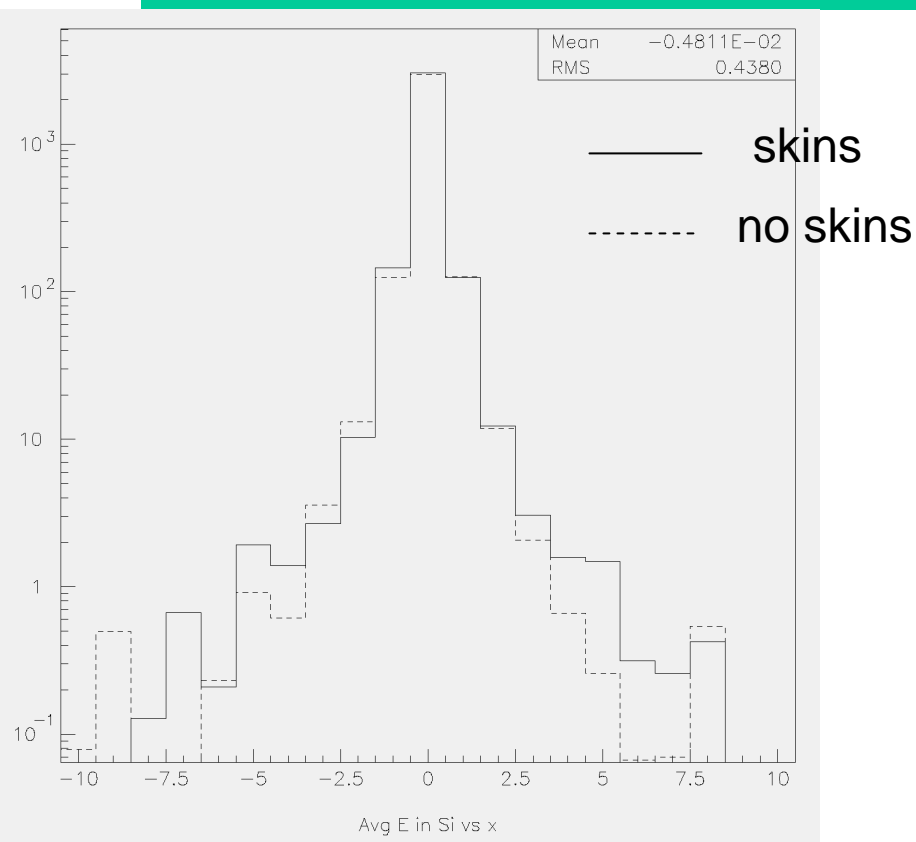
Presumably the same issue exists for Geant4 (range cut)

# Do we need the “skins” in this case?

- 10 GeV photons
- about 3x more CPU time



# transverse spatial distributions (5 GeV photons)

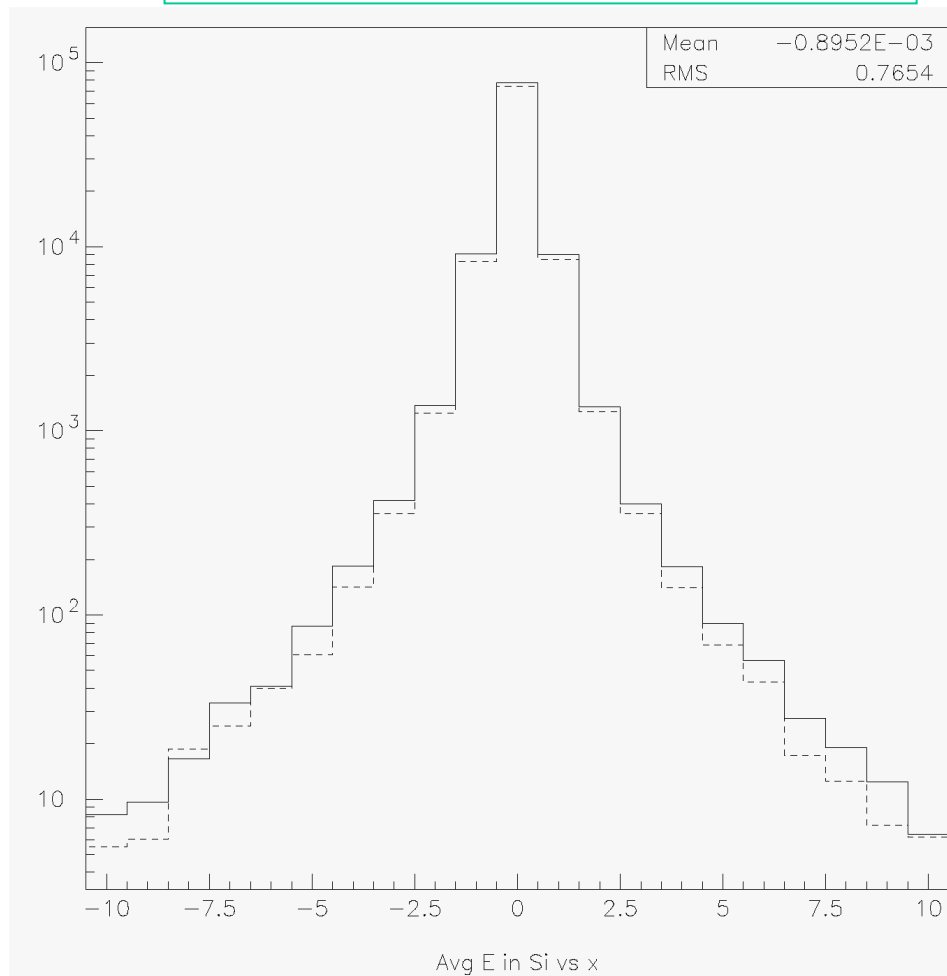


E vs x at layer 4

Note: rms is 0.44 pixel (2,2 mm)

E vs x: all layers

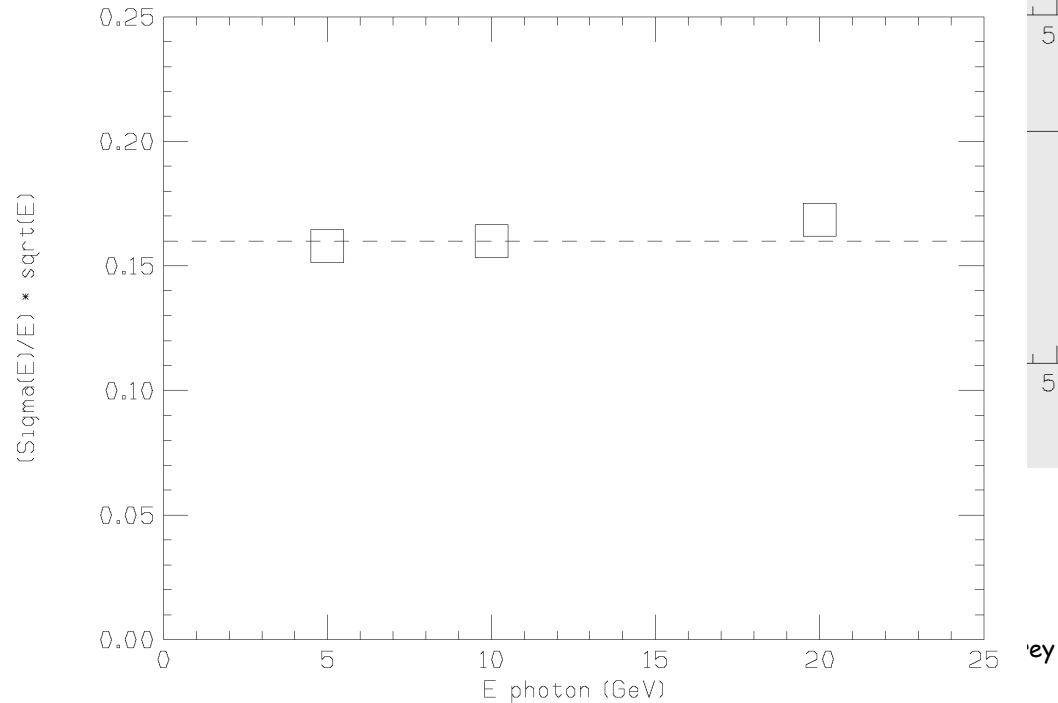
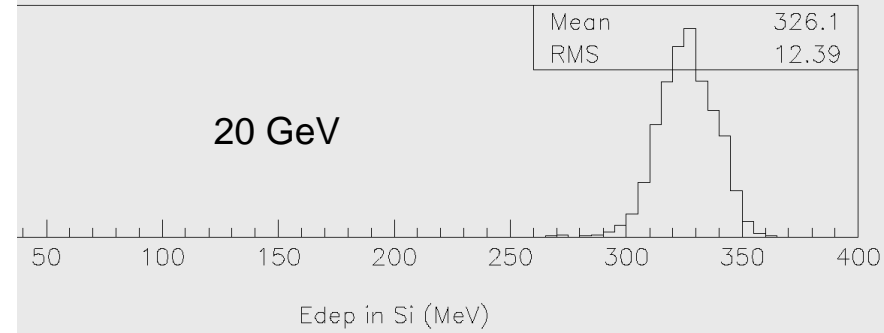
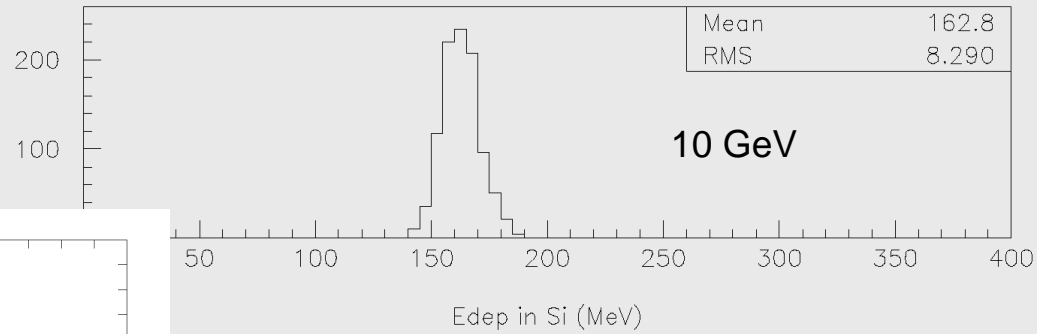
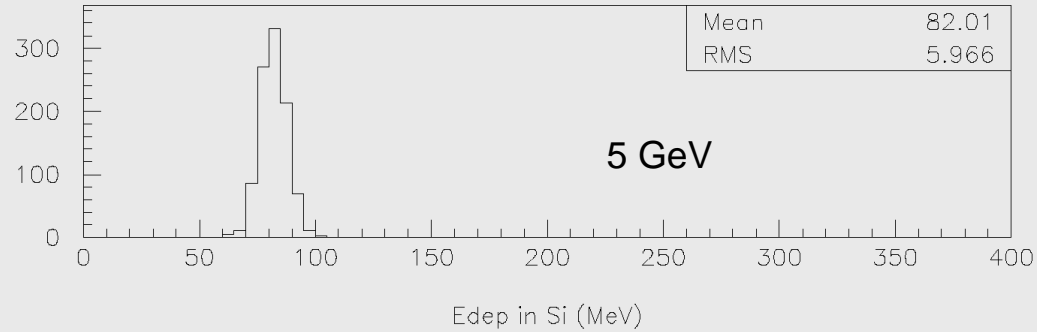
About a 20-25% difference



# energy resolution (photons)

use rms for width:

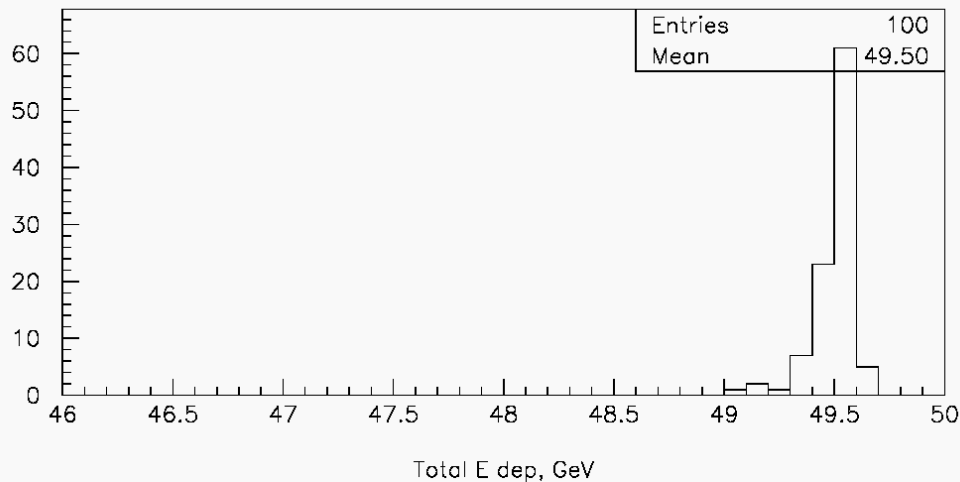
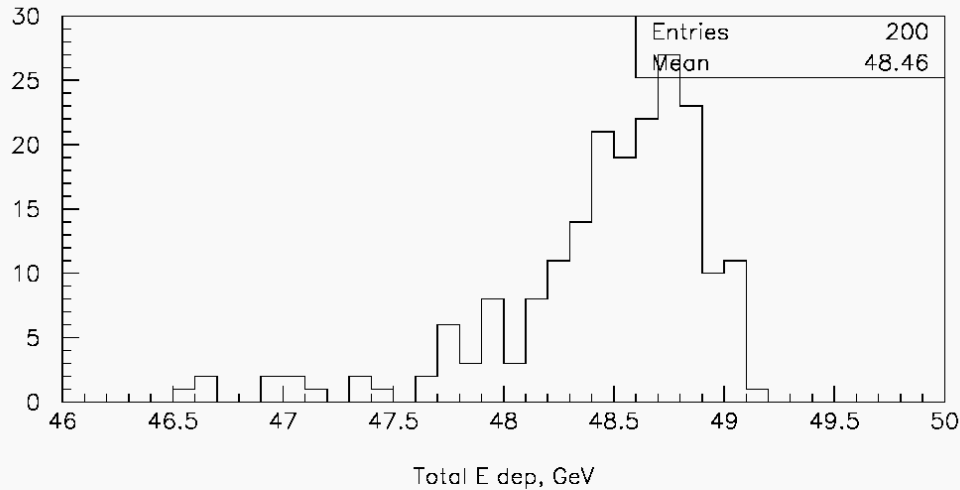
$$0.16/\sqrt{E}$$



# Alternative Sampling Configurations – old study

50 GeV electrons

$30 \times 5/7 X_0$



$20 \times 5/7 X_0 + 10 \times 10/7 X_0$

- better containment
- poorer sampling